Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-12-15
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Patrick Crudo	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 688 339	Representative Email *	patrick.crudo@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F410RBT6	P05W*458XXXA	A	9998	2016-12-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	307.98	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L bend	
Comment	L QFP 64 10x10x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-20th June 2016	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P05W*458XXXA					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	6.362	mg	supplier	die	Silicon (Si)	7440-21-3		5.911	mg	929110	19193
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	3458	71
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.142	mg	22320	461
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.158	mg	24835	513
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.064	mg	10060	208
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.017	mg	2672	55
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.048	mg	7545	156
LEADFRAME (MHT- C194)	Other inorganic materials	47.409	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		46.200	mg	974503	150011
LEADFRAME (MHT- C194)				supplier	ALLOY	Iron (Fe)	7439-89-6		1.138	mg	24002	3695
LEADFRAME (MHT- C194)				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.057	mg	1198	184
LEADFRAME (MHT- C194)				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.014	mg	297	46
LEADFRAME (MHT- Ag)	Other inorganic materials	1.103	mg	supplier	COATING	Silver(Ag)	7440-22-4		1.103	mg	1000000	3580
DIE ATTACH (Evertech -AP4200)	Other inorganic materials	0.009	mg	supplier	GLUE	Epoxy	9003-36-5		0.002	mg	222222	6
DIE ATTACH (Evertech -AP4200)				supplier	GLUE	Silver(Ag)	7440-22-4		0.007	mg	777778	23
BONDING WIRE (MKE - Au wire)	Other inorganic materials	1.085	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.084	mg	999078	3520
BONDING WIRE (MKE - Au wire)				supplier	BONDING WIRE	Palladium (Pd)	7440-41-7		0.001	mg	922	3
ENCAPSULATION (Sumitomo -G631HC	Other inorganic materials	248.521	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		25.384	mg	102140	82421
ENCAPSULATION (Sumitomo -G631HC				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		207.907	mg	836577	675065
ENCAPSULATION (Sumitomo -G631HC				supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		13.961	mg	56176	45331
ENCAPSULATION (Sumitomo -G631HC				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		1.269	mg	5106	4120
FINISHING- (ST380 -Sn)	Other inorganic materials	3.492	mg	supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		3.492	mg	1000000	11338